IPC ASSOCIATION CONNE ELECTRONICS INDUS	Material Comp © Copyright 2005. I international and Pa	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					Ifg Informati	on		
Supplier Info															
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
onsemi											2025-07	2025-07-03			
Contact Name		Title - Contact			1	Phone - Contact*				Email - Contact*					
Product-Env-Sto	ewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Repr	esentative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-Env-St	ewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Requ	ester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	e Versio	on I	Manufacturing Site		Weight*	UOM	Unit Type	
		FOD411	FOD4118SDV 6PB ZC SNUB T&R V		kR VDE		2025-07-03		ТНН			537.109	mg	Each	
Ianufacturii	ng Proccess Informa	ntion												·	
Terminal Plating / Grid Array Material			Ferminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temper		Temperatu			ture Numb	er of Reflow Cyc	eles		
Matte	Tin (Sn) - annealed	(CU Alloy	1			260		C	30	secor	nds 3			
omments															
vel 1 - maximu	m time at peak temperat	ure during sol	dering is 10-3	30 seconds											
or more inform	ation regarding material	composition	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Level Substance		Exempt	Weight	Unit of Measure
Coupling Gel	1.83	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.635	mg
			Supplier	Dimethyl Siloxane	68083-19-2		0.888	mg
			Supplier	3-Methacryloxypropyltrimethoxysilane (C10H20O5Si)	2530-85-0		0.307	mg
Die	4.043	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.283	mg
			Supplier	Silicon (Si)	7440-21-3		3.76	mg
Die Attach	1.665	mg	Supplier	Silver (Ag)	7440-22-4		1.2487	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.4162	mg
Lead Frame	108.322	mg	Supplier	Silver (Ag)	7440-22-4		0.68	mg
			Supplier	Zinc (Zn)	7440-66-6		0.13	mg
			Supplier	Iron (Fe)	7439-89-6		2.48	mg
			Supplier	Copper (Cu)	7440-50-8		105	mg
			Supplier	Phosphorus (P)	7723-14-0		0.032	mg
Mold Compound-Black	414.4	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		16.6	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		95.3998	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		12.4	mg
			Supplier	Carbon Black (C)	1333-86-4		4.15	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		285.8498	mg
Plating	6.7	mg	Supplier	Tin (Sn)	7440-31-5		6.7	mg
Wire Bond - Au	0.149	mg	Supplier	Gold (Au)	7440-57-5		0.149	mg